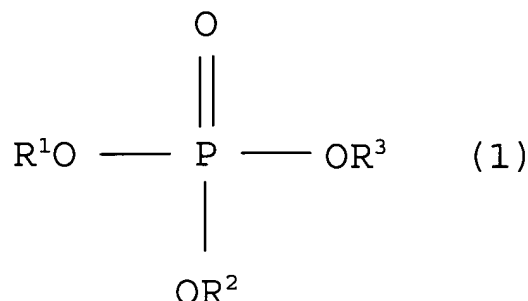


# AMENDMENTS TO THE CLAIMS

Please amend the Claims as follows. Deletions are ~~struck through~~. Please add Claims 15-18.

1 (original): An inorganic powder-containing resin composition comprising inorganic powder, a binder resin, and a phosphorus compound represented by formula (1):



wherein  $\text{R}^1$ ,  $\text{R}^2$  and  $\text{R}^3$  independently represent H, an alkyl group, an alkylaryl group,  $\text{NH}_4^+$  (ammonium) or  $-(\text{CH}_2\text{CH}_2\text{O})_n-\text{R}^4$ , wherein n is 1 to 15, and  $\text{R}^4$  represents H, an alkyl group, an alkylaryl group or a (meth)acryloyl group.

2 (original): The inorganic powder-containing resin composition according to claim 1, wherein the weight-average molecular weight of the binder resin is 50,000 to 500,000.

3 (currently amended): The inorganic powder-containing resin composition according to claim 1 ~~or~~ 2, wherein the binder resin is (meth)acrylic resin.

4 (original): The inorganic powder-containing resin composition according to claim 3, wherein the (meth)acrylic resin has a carboxyl group.

5 (original): The inorganic powder-containing resin composition according to claim 4, wherein the (meth)acrylic resin has an acid value of 0.5 to 5 KOH mg/g.

6 (currently amended): The inorganic powder-containing resin composition according to claim 1 ~~to~~ 5, wherein 5 to 50 parts by weight of the binder resin and 0.1 to 10 parts by weight of the phosphorus compound relative to 100 parts by weight of the inorganic powder are contained.

7 (currently amended): The inorganic powder-containing resin composition according to claim 1 ~~to~~ 6, wherein the inorganic powder is glass powder.

8 (currently amended): The inorganic powder-containing resin composition according to claim 1 ~~to~~ 7, wherein the viscosity of the inorganic powder at 600°C is 150 Pa·s or less.

9 (currently amended): The inorganic powder-containing resin composition according to claim 1 ~~to~~ 8, which is used as a material forming a dielectric layer.

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10 (currently amended): A film-forming material layer comprising the inorganic powder-containing resin composition according to claim 1 to 9 formed in a sheet form.

11 (original): A transfer sheet comprising at least the film-forming material layer according to claim 10 laminated on a support film.

12 (original): A dielectric layer comprising the film-forming material layer according to claim 10 sintered therein.

13 (original): A method of producing a substrate having a dielectric layer formed thereon, comprising the step of transferring the film-forming material layer of the transfer sheet according to claim 11 onto a substrate and the step of sintering the transferred film-forming material layer at 550 to 650°C to form a dielectric layer on the substrate.

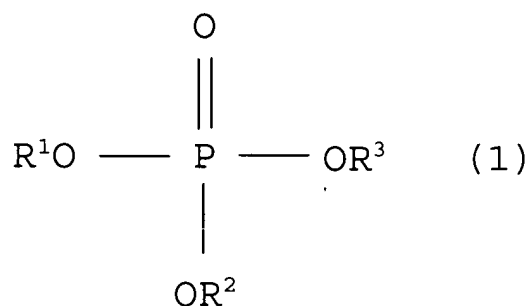
14 (original): A substrate having a dielectric layer formed thereon, which is produced according to the method of claim 13.

15 (new): An inorganic powder-containing resin composition which is sinterable and comprises:

100 parts by weight of inorganic powder;

5 to 50 parts by weight of a binder resin; and

0.1 to 10 parts by weight of a phosphorus compound represented by formula (1):



wherein  $\text{R}^1$ ,  $\text{R}^2$  and  $\text{R}^3$  independently represent H, an alkyl group, an alkylaryl group,  $\text{NH}_4^+$  (ammonium) or  $-(\text{CH}_2\text{CH}_2\text{O})_n-\text{R}^4$ , wherein n is 1 to 15, and  $\text{R}^4$  represents H, an alkyl group, an alkylaryl group or a (meth)acryloyl group.

16 (new): The inorganic powder-containing resin composition according to claim 15, wherein at least one of  $\text{R}^1$ ,  $\text{R}^2$  and  $\text{R}^3$  is H.

17 (new): The inorganic powder-containing resin composition according to claim 15, wherein the binder resin is a (meth)acrylic resin having a carboxyl group and has an acid value of 0.5 to 5 KOH mg/g.

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18 (new): The inorganic powder-containing resin composition according to claim 15,  
wherein the inorganic powder has a softening point of 400 to 650°C.